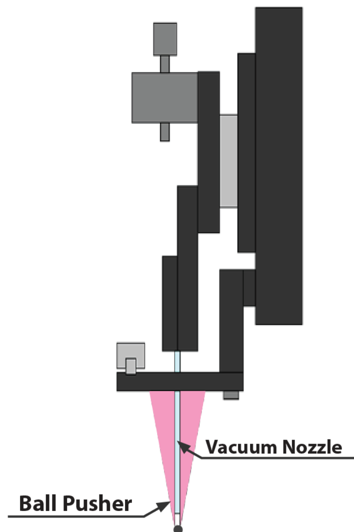
Process Equipment

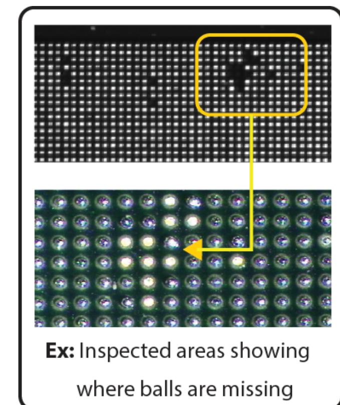
Microball

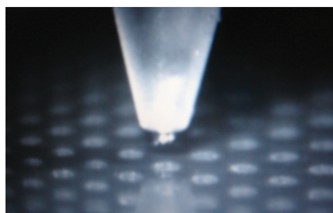
Packaging Device

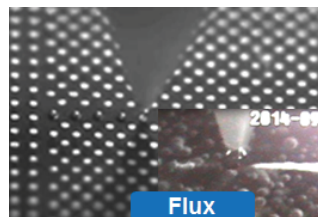


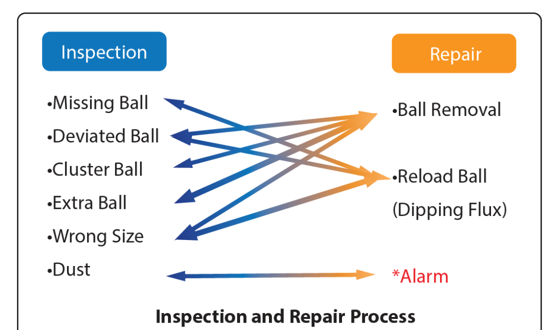
Specifications

Micro Ball Inspection and Repair System		
Ball Size	φ40μm～φ500μm （**Minimum:** 10μm option available)	
Max Substrate Size	PCB:500㎜×500㎜, Si Wafer：12”	
Tact Time (Inspection)	**Approx.** 20sec（PCB300㎜×400㎜)/(Repair)（**Ball Placing**):1~1.5sec/ 1 ball repair	
Items that can be inspected & repaired *Dust repair not possible	•Missing Ball •Cluster Ball •Wrong Ball Size	•Deviated Ball •Extra Ball •Contamination (Dust)*


Ex: Inspected areas showing where balls are missing


Pusher Needle visible from nozzle (Top Image)





Inspection and Repair Process

SEIWA OPTICAL

SEIWA OPTICAL AMERICA INC
3042 Scott Blvd
Santa Clara, CA 95054

Tel: +408 - 844 - 8008
Fax: +408 - 844 - 8944
http://www.seiwaamerica.com